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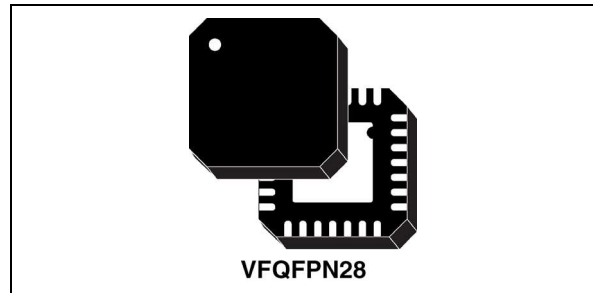
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Multi-band RF frequency synthesizer with integrated VCOs

Features

- Integer-N frequency synthesizer
- Dual differential integrated VCOs with automatic center frequency calibration:
 - 3000 - 3620 MHz (direct output)
 - 4000 - 4650 MHz (direct output)
 - 1500 - 1810 MHz (internal divider by 2)
 - 2000 - 2325 MHz (internal divider by 2)
 - 750 - 905 MHz (internal divider by 4)
 - 1000 - 1162.5 MHz (internal divider by 4)
- Excellent integrated phase noise
- Fast lock time: 150 μ s
- Dual modulus programmable prescaler (16/17 or 19/20)
- 2 programmable counters to achieve a feedback division ratio from 256 to 65551 (prescaler 16/17) and from 361 to 77836 (prescaler 19/20).
- Programmable reference frequency divider (10 bits)
- Phase frequency comparator and charge pump
- Programmable charge pump current
- Digital lock detector
- Dual digital bus Interface: SPI and I²C bus with 3 bit programmable address (1100A₂A₁A₀)
- 3.3V power supply
- Power down mode (HW and SW)
- Small size exposed pad VFQFPN28 package 5x5x1.0mm
- Process: BICMOS 0.35 μ m SiGe

**Applications**

- 2.5G and 3G cellular infrastructure equipment
- CATV equipment
- Instrumentation and test equipment
- Other wireless communication systems

Description

The STMicroelectronics STW81102 is an integrated RF synthesizer with voltage controlled oscillators (VCOs). Showing high performance, high integration, low power, and multi-band performances, the STW81102 is a low-cost one-chip alternative to discrete PLL and VCOs solutions.

The STW81102 includes an Integer-N frequency synthesizer and two fully integrated VCOs featuring low phase noise performance and a noise floor of -155 dBc/Hz.

The combination of wide frequency range VCOs (using center-frequency calibration over 32 sub-bands) and multiple output options (direct output, divided by 2 or divided by 4) allows coverage from 750 MHz to 905 MHz and 1000MHz to 1162.5 MHz, from 1500MHz to 1810 MHz and 2000 MHz to 2325MHz, from 3000 MHz to 3620 MHz and 4000MHz to 4650 MHz bands.

The STW81102 is designed with STMicroelectronics advanced 0.35 μ m SiGe process.

Contents

- 1 Block diagram and pin configuration 6**
 - 1.1 Block diagram 6
 - 1.2 Pin configuration 7

- 2 Electrical specifications 9**
 - 2.1 Absolute maximum ratings 9
 - 2.2 Operating conditions 9
 - 2.3 Digital logic levels 10
 - 2.4 Electrical specifications 10
 - 2.5 Phase noise specification 13

- 3 Typical performance characteristics 15**

- 4 General description 18**

- 5 Circuit description 19**
 - 5.1 Reference input stage 19
 - 5.2 Reference divider 19
 - 5.3 Prescaler 19
 - 5.4 A and B counters 20
 - 5.5 Phase frequency detector (PFD) 21
 - 5.6 Lock detect 21
 - 5.7 Charge pump 21
 - 5.8 Voltage controlled oscillators 23
 - 5.8.1 VCO selection 23
 - 5.8.2 VCO frequency calibration 23
 - 5.8.3 VCO voltage amplitude control 24
 - 5.9 Output stage 25
 - 5.9.1 Output Buffer control mode 25
 - 5.10 External VCO Buffer 26

- 6 I²C bus interface 27**
 - 6.1 General features 27

6.1.1	Data validity	27
6.1.2	START and STOP conditions	27
6.1.3	Byte format and acknowledge	28
6.1.4	Device addressing	28
6.1.5	Single-byte write mode	29
6.1.6	Multi-byte write mode	29
6.1.7	Current byte address read mode	29
6.2	Timing specification	30
6.3	I ² C registers	32
6.3.1	Write-only registers	32
6.3.2	Read-only register	34
6.3.3	Default configuration	34
6.4	VCO calibration procedure	35
6.4.1	VCO calibration auto-restart feature	35
7	SPI digital interface	36
7.1	General features	36
7.2	Timing specification	37
7.3	Bit tables	38
7.3.1	Default configuration	40
7.4	VCO calibration procedure	40
7.4.1	VCO calibration auto-restart feature	40
8	Application information	41
8.1	Direct output	41
8.2	Divided by 2 output	43
8.3	Divided by 4 output	45
8.4	Evaluation kit	46
9	Application diagrams	47
10	Package mechanical data	50
11	Ordering information	52
12	Revision history	52

List of tables

Table 1.	Pin description	7
Table 2.	Absolute maximum ratings	9
Table 3.	Operating conditions (refer to <i>Figure 36: Typical application diagram</i>)	9
Table 4.	Digital logic levels	10
Table 5.	Electrical specifications.	10
Table 6.	Phase noise specification	13
Table 7.	Current value vs. selection	22
Table 8.	VCO A performances versus amplitude setting (freq=3.3GHz)	24
Table 9.	VCO B performances versus amplitude setting (freq=4.3GHz)	25
Table 10.	EXT_PD pin function setting.	25
Table 11.	Single-byte write mode	29
Table 12.	Multi-byte write mode	29
Table 13.	Current byte address read mode	29
Table 14.	Data and clock timing specifications.	30
Table 15.	Start and stop timing specifications	31
Table 16.	Ack timing specifications.	31
Table 17.	Write-only registers.	32
Table 18.	Functional modes	32
Table 19.	SPI data structure (MSB is sent first)	37
Table 20.	Address decoder and outputs.	37
Table 21.	SPI timing specification.	37
Table 22.	Bits at 00h and ST1	38
Table 23.	Bits at 01h and ST2	39
Table 24.	Order code of the evaluation kit	46
Table 25.	Package dimensions.	51
Table 26.	Order codes	52
Table 27.	Document revision history	52

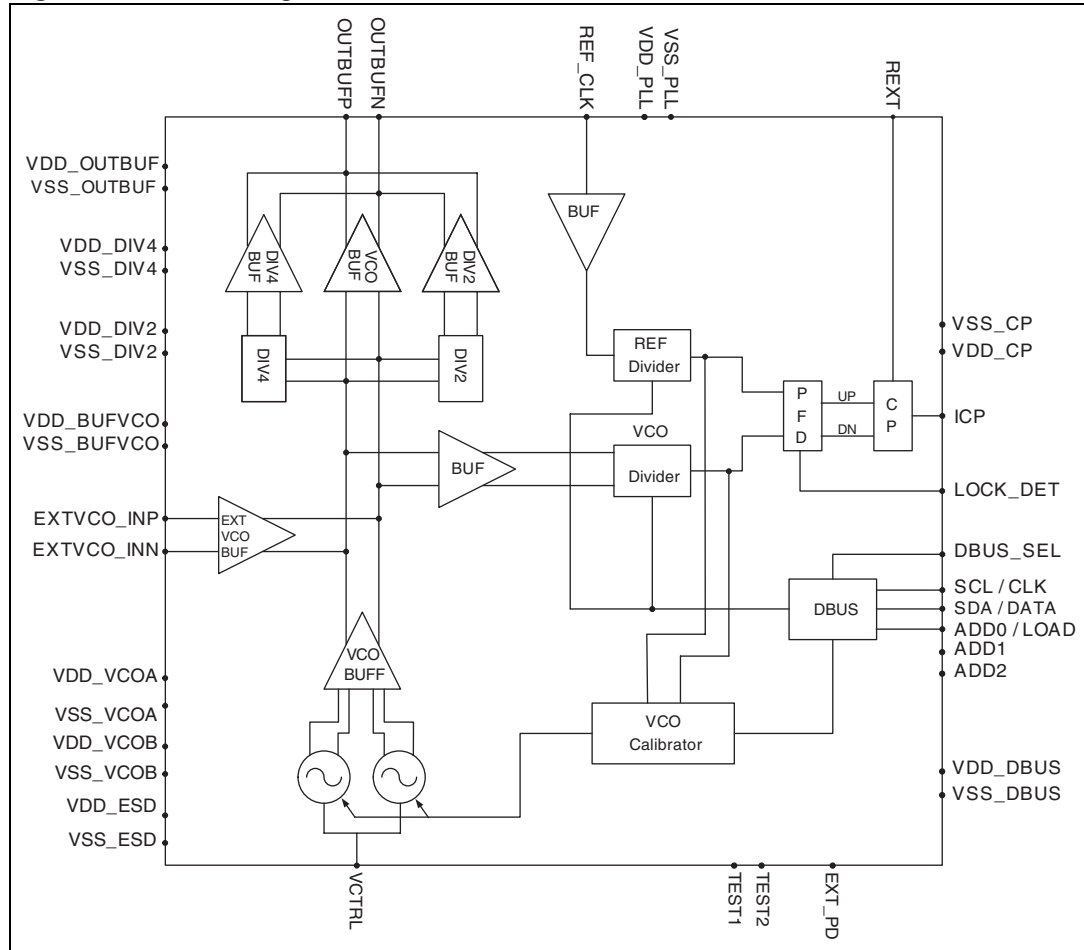
List of figures

Figure 1.	Block diagram	6
Figure 2.	Pin connection (top view)	7
Figure 3.	VCO A (direct output) open loop phase noise	15
Figure 4.	VCO B (direct output) open loop phase noise	15
Figure 5.	VCO A (direct output) closed loop phase noise at 3.6GHz ($F_{STEP}=200\text{kHz}$; $F_{PFD}=200\text{kHz}$; $I_{CP}=3\text{mA}$)	15
Figure 6.	VCO B (direct output) closed loop phase noise at 4.3GHz ($F_{STEP}=200\text{kHz}$; $F_{PFD}=200\text{kHz}$; $I_{CP}=4\text{mA}$)	15
Figure 7.	VCO A (div. by 2 output) closed loop phase noise at 1.65GHz ($F_{STEP}=200\text{kHz}$; $F_{PFD}=400\text{kHz}$; $I_{CP}=2\text{mA}$)	16
Figure 8.	VCO B (div. by 2 output) closed loop phase noise at 2.15GHz ($F_{STEP}=200\text{kHz}$; $F_{PFD}=400\text{kHz}$; $I_{CP}=3\text{mA}$)	16
Figure 9.	VCO A (div. by 4 output) closed loop phase noise at 825MHz ($F_{STEP}=200\text{kHz}$; $F_{PFD}=800\text{kHz}$; $I_{CP}=1.5\text{mA}$)	16
Figure 10.	VCO B (div. by 4 output) closed loop phase noise at 1.075GHz ($F_{STEP}=200\text{kHz}$; $F_{PFD}=800\text{kHz}$; $I_{CP}=2.5\text{mA}$)	16
Figure 11.	PFD frequency spurs (direct output; $F_{PFD}=200\text{kHz}$)	17
Figure 12.	PFD frequency spurs (div. by 2 output; $F_{PFD}=400\text{kHz}$)	17
Figure 13.	PFD frequency spurs (div. by 4 output; $F_{PFD}=800\text{kHz}$)	17
Figure 14.	Settling time (final frequency=2.15 GHz; $F_{PFD}=400\text{kHz}$; $I_{CP}=3\text{mA}$)	17
Figure 15.	Reference frequency input buffer	19
Figure 16.	VCO divider diagram	20
Figure 17.	PFD diagram	21
Figure 18.	Loop filter connection	22
Figure 19.	VCO sub-bands frequency characteristics	23
Figure 20.	Data validity	27
Figure 21.	START and STOP conditions	28
Figure 22.	Byte format and acknowledge	28
Figure 23.	Data and clock	30
Figure 24.	Start and stop	30
Figure 25.	Ack	31
Figure 26.	SPI input and output bit order	36
Figure 27.	SPI timing specification	37
Figure 28.	Differential/single-ended output network (MATCH_LC_LUMP_4G_DIFF.dsn)	41
Figure 29.	LC lumped balun and matching network (MATCH_LC_LUMP_4G.dsn)	42
Figure 30.	Evaluation board (EVB4G) matching network (MATCH_EVB4G.dsn)	43
Figure 31.	Differential/single-ended output network (MATCH_LC_LUMP_2G_DIFF.dsn)	43
Figure 32.	LC lumped balun for divided by 2 output (MATCH_LC_LUMP_2G.dsn)	44
Figure 33.	Evaluation board (EVB2G) matching network (MATCH_EVB2G.dsn)	44
Figure 34.	LC lumped balun for divided by 4 output (MATCH_LC_LUMP_1G.dsn)	45
Figure 35.	Evaluation board (EVB1G) matching network (MATCH_EVB1G.dsn)	46
Figure 36.	Typical application diagram	47
Figure 37.	Ping-pong architecture diagram	48
Figure 38.	Application diagram with external VCO (LO output from STW81102)	49
Figure 39.	Application diagram with external VCO (LO output from VCO)	49
Figure 40.	VFQFPN28 mechanical drawing (<i>Note 1</i>)	50

1 Block diagram and pin configuration

1.1 Block diagram

Figure 1. Block diagram



1.2 Pin configuration

Figure 2. Pin connection (top view)

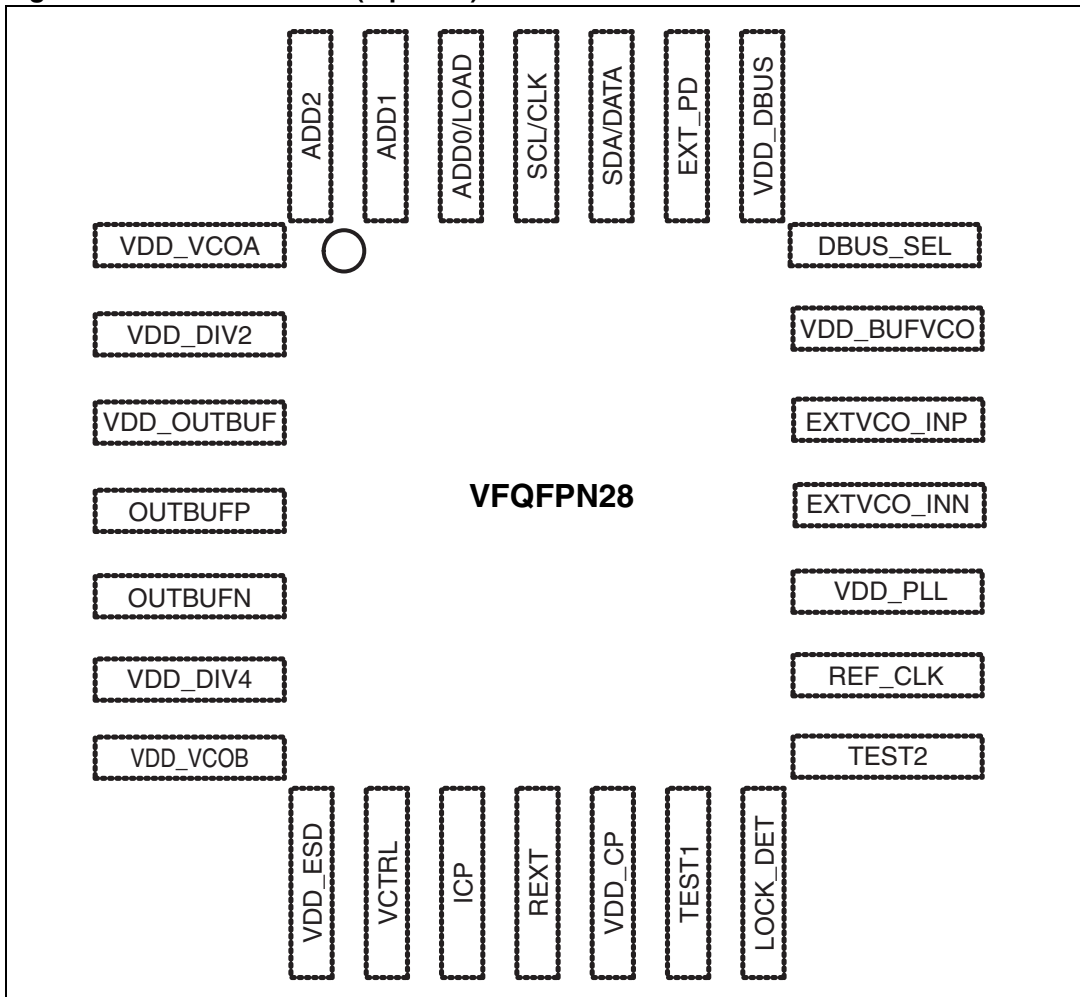


Table 1. Pin description

Pin No	Name	Description	Observation
1	VDD_VCOA	VCOA power supply	
2	VDD_DIV2	Divider by 2 power supply	
3	VDD_OUTBUF	Output buffer power supply	
4	OUTBUFP	LO buffer positive output	Open collector
5	OUTBUFN	LO buffer negative output	Open collector
6	VDD_DIV4	Divider by 4 power supply	
7	VDD_VCOB	VCOB power supply	
8	VDD_ESD	ESD positive rail power supply	
9	VCTRL	VCO control voltage	
10	ICP	PLL charge pump output	

Table 1. Pin description (continued)

Pin No	Name	Description	Observation
11	REXT	External resistance connection for PLL charge pump	
12	VDD_CP	Power supply for charge pump	
13	TEST1	Test input 1	For test purposes only; must be connected to GND
14	LOCK_DET	Lock detector	CMOS output (I _{OUT} = 4 mA)
15	TEST2	Test input 2	For test purposes only; must be connected to GND
16	REF_CLK	Reference clock input	
17	VDD_PLL	PLL digital power supply	
18	EXTVCO_INN	External VCO negative input	For test purposes only; must be connected to GND
19	EXTVCO_INP	External VCO positive input	For test purposes only; must be connected to GND
20	VDD_BUFVCO	VCO buffer power supply	
21	DBUS_SEL	Digital bus interface select	CMOS input
22	VDD_DBUS	SPI and I ² C bus power supply	
23	EXT_PD	Power down hardware '0' device ON; '1' device OFF	CMOS input
24	SDA/DATA	I2CBUS/SPI data line	CMOS Bidir Schmitt triggered (I _{OUT} =4 mA)
25	SCL/CLK	I2CBUS/SPI clock line	CMOS input Schmitt triggered
26	ADD0/LOAD	I2CBUS address select pin/ SPI load line	CMOS input
27	ADD1	I2CBUS address select pin	CMOS input; must be connected to GND in SPI mode
28	ADD2	I2CBUS address select pin	CMOS input; must be connected to GND in SPI mode

2 Electrical specifications

2.1 Absolute maximum ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Values	Unit
AV_{CC}	Analog supply voltage	0 to 4.6	V
DV_{CC}	Digital supply voltage	0 to 4.6	V
T_{stg}	Storage temperature	-65 to 150	°C
ESD	Electrical static discharge		
	- HBM ⁽¹⁾	4	kV
	- CDM-JEDEC standard	1.5	
- MM	0.2		

1. The maximum rating of the ESD protection circuitry on pin 4 and pin 5 is 800V.

2.2 Operating conditions

Table 3. Operating conditions (refer to [Figure 36: Typical application diagram](#))

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
AV_{DD}	Analog supply voltage		3.0	3.3	3.6	V
DV_{DD}	Digital supply voltage		3.0	3.3	3.6	V
I_{VDD1}	V_{DD1} current consumption			90		mA
I_{VDD2}	V_{DD2} current consumption			12		mA
T_{amb}	Operating ambient temperature		-40		85	°C
T_j	Maximum junction temperature				125	°C
$R_{th\ j-amb}$	Junction to ambient package thermal resistance	Multilayer JEDEC board		35		°C/W
$R_{th\ j-b}$	Junction to board package thermal resistance	Multilayer JEDEC board		26.3		°C/W
$R_{th\ j-c}$	Junction to case package thermal resistance	Multilayer JEDEC board		6.3		°C/W

2.3 Digital logic levels

Table 4. Digital logic levels

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{il}	Low level input voltage				$0.2 \cdot V_{dd}$	V
V_{ih}	High level input voltage		$0.8 \cdot V_{dd}$			V
V_{hyst}	Schmitt trigger hysteresis		0.8			V
V_{ol}	Low level output voltage				0.4	V
V_{oh}	High level output voltage		$0.85 \cdot V_{dd}$			V

2.4 Electrical specifications

All the electrical specifications are intended at 3.3V supply voltage.

Table 5. Electrical specifications

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
Output frequency range						
F_{OUTA}	Output frequency range with VCOA	Direct output	3000		3620	MHz
		Divider by 2	1500		1810	MHz
		Divider by 4	750		905	MHz
F_{OUTB}	Output frequency range with VCOB	Direct output	4000		4650	MHz
		Divider by 2	2000		2325	MHz
		Divider by 4	1000		1162.5	MHz
VCO dividers						
N	VCO divider ratio	Prescaler 16/17	256		65551	
		Prescaler 19/20	361		77836	
Reference clock and phase frequency detector						
F_{ref}	Reference input frequency		10		200	MHz
	Reference input sensitivity ⁽¹⁾		0.35	1	1.5	V _{peak}
R	Reference divider ratio		2		1023	
F_{PFD}	PFD input frequency				16	MHz
F_{STEP}	Frequency step ⁽²⁾	Prescaler 16/17	$F_{OUT}/65551$		$F_{OUT}/256$	Hz
		Prescaler 19/20	$F_{OUT}/77836$		$F_{OUT}/361$	Hz
Charge pump						
I_{CP}	ICP sink/source ⁽³⁾	3bit programmable			5	mA
V_{OCP}	Output voltage compliance range		0.4		$V_{dd}-0.3$	V

Table 5. Electrical specifications (continued)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
	Spurious ⁽⁴⁾	Direct output ($F_{PFD} = 200 \text{ kHz}$)		-73		dBc
		Divider by 2 ($F_{PFD} = 400 \text{ kHz}$)		-83		dBc
		Divider by 4 ($F_{PFD} = 800 \text{ kHz}$)		-91		dBc
VCOs						
K_{VCOA}	VCOA sensitivity ⁽⁵⁾	Lower frequency range	40	55	70	MHz/V
		Intermediate frequency range	60	75	95	MHz/V
		Higher frequency range	80	105	140	MHz/V
K_{VCOB}	VCOB sensitivity ⁽⁵⁾	Lower frequency range	30	45	60	MHz/V
		Intermediate frequency range	40	55	70	MHz/V
		Higher frequency range	50	70	90	MHz/V
ΔT_{LK}	Maximum temperature variation for continuous lock ⁽⁵⁾⁽⁶⁾	VCO A	115			°C
		VCO B	95			
	VCO A pushing ⁽⁵⁾			4	7	MHz/V
	VCO B pushing ⁽⁵⁾			14	20	MHz/V
V_{CTRL}	VCO control voltage ⁽⁵⁾		0.4		3	V
	LO harmonic spurious ⁽⁵⁾				-20	dBc
I_{VCOA}	VCOA current consumption	$F_{VCO}=3.3\text{GHz}$; amplitude [11]		30		mA
		$F_{VCO}=3.3\text{GHz}$; amplitude [00]		16		mA
I_{VCOB}	VCOB current consumption	$F_{VCO}=4.3\text{GHz}$; amplitude [11]		22		mA
		$F_{VCO}=4.3\text{GHz}$; amplitude [00]		11		mA
I_{VCOBUF}	VCO buffer consumption			15		mA
I_{DIV2}	Divider by 2 consumption			17		mA
I_{DIV4}	Divider by 4 consumption			13		mA
LO output buffer						
P_{LO}	Output level			0		dBm
R_L	Return loss ⁽⁵⁾	Matched to 50 ohms		15		dB
I_{OUTBUF}	Current consumption	DIV4 buff		27		mA
		DIV2 buff		23		mA
		Direct output		39		mA
	Output buffer isolation (power down state)	Direct output ($F_{OUT}=4\text{GHz}$)		43		dB
		Divider by 2 output ($F_{OUT}=2\text{GHz}$)		62		
		Divider by 4 output ($F_{OUT}=1\text{GHz}$)		67		

Table 5. Electrical specifications (continued)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
External VCO						
	Frequency range		0.625		5	GHz
	Input level		-10		+6	dBm
	Current consumption	VCO internal buffer		28		mA
PLL miscellaneous						
I_{PLL}	Current consumption	Input buffer, prescaler, digital dividers, misc.		12		mA
t_{lock}	Lock up time ^{(5), (7)}	25kHz PLL bandwidth; within 1 ppm of frequency error		150		μ s

- In order to achieve best phase noise performance 1V peak level is suggested.
- The frequency step is related to the PFD input frequency as follows:
 - $F_{STEP} = F_{PFD}$ for direct output
 - $F_{STEP} = F_{PFD}/2$ for divided by 2 output
 - $F_{STEP} = F_{PFD}/4$ for divided by 4 output
- See relationship between ICP and REXT in [Section 5.7: Charge pump](#).
- The level of the spurs may change depending on PFD frequency, charge pump current, selected channel and PLL loop BW.
- Guaranteed by design and characterization.
- When setting a specified output frequency, the VCO calibration procedure must be run in order to select the best sub-range for the VCO covering the desired frequency. Once programmed at the initial temperature T_0 inside the operating temperature range (-40 °C to +85 °C), the synthesizer is able to maintain the lock status only if the temperature drift (in either direction) is within the limit specified by ΔT_{LK} , provided that the final temperature T_1 is still inside the nominal range. If higher ΔT are required the "**VCO calibration auto-restart**" feature can be enabled, thus allowing to re-start the VCO calibration procedure automatically when the part loose the lock condition (trigger on lock detector signal)
- Frequency jump from 2300 to 2150 MHz; it includes the time required by the VCO calibration procedure (7 F_{PFD} cycles with $F_{PFD}=400$ kHz).

2.5 Phase noise specification

Table 6. Phase noise specification

Parameter	Test conditions	Min	Typ	Max	Unit
Phase noise performance⁽¹⁾					
Inband phase noise floor – closed loop⁽²⁾					
Normalized inband phase noise floor	ICP=4mA, PLL BW = 50kHz; including reference clock contribution		-222		dBc/Hz
Inband phase noise floor direct output	ICP=4mA, PLL BW = 50kHz; including reference clock contribution	-222+20log(N)+10log(F _{PFD})			dBc/Hz
Inband phase noise floor divider by 2		-228+20log(N)+10log(F _{PFD})			dBc/Hz
Inband phase noise floor divider by 4		-234+20log(N)+10log(F _{PFD})			dBc/Hz
PLL integrated phase noise – direct output					
Integrated phase noise 100 Hz to 40 MHz	F _{OUT} = 4.3 GHz, F _{PFD} = 200kHz, F _{STEP} =200 kHz, PLL BW = 15kHz, ICP=4mA		-35		dBc
			1.4		° rms
PLL integrated phase noise – divider by 2					
Integrated phase noise 100Hz to 40MHz	F _{OUT} = 2.15 GHz, F _{PFD} = 400kHz, F _{STEP} =200 kHz, PLL BW = 20kHz, ICP=3mA		-44		dBc
			0.52		° rms
PLL integrated phase noise – divider by 4					
Integrated phase noise 100Hz to 40MHz	F _{OUT} = 1.075 GHz, F _{PFD} = 800kHz, F _{STEP} =200 kHz, PLL BW = 30kHz, ICP=2.5mA		-51		dBc
			0.22		° rms
VCO A direct (3000MHz-3620MHz) – open loop⁽³⁾					
Phase noise @ 1 kHz			-57		dBc/Hz
Phase noise @ 10 kHz			-84		dBc/Hz
Phase noise @ 100 kHz			-107		dBc/Hz
Phase noise @ 1 MHz			-129		dBc/Hz
Phase noise @ 10 MHz			-149		dBc/Hz
Phase noise @ 40 MHz			-159		dBc/Hz
VCO B direct (4000MHz-4650MHz) – open loop⁽³⁾					
Phase noise @ 1 kHz			-55		dBc/Hz
Phase noise @ 10 kHz			-83		dBc/Hz
Phase noise @ 100 kHz			-106		dBc/Hz
Phase noise @ 1 MHz			-128		dBc/Hz
Phase noise @ 10 MHz			-148		dBc/Hz
Phase noise @ 40 MHz			-158		dBc/Hz

Table 6. Phase noise specification (continued)

Parameter	Test conditions	Min	Typ	Max	Unit
VCO A with divider by 2 (1500MHz-1810MHz) – open loop⁽³⁾					
Phase noise @ 1 kHz			-63		dBc/Hz
Phase noise @ 10 kHz			-90		dBc/Hz
Phase noise @ 100 kHz			-113		dBc/Hz
Phase noise @ 1 MHz			-135		dBc/Hz
Phase noise @ 10 MHz			-151.5		dBc/Hz
Phase noise floor @ 40 MHz			-155		dBc/Hz
VCO B with divider by 2 (2000MHz-2325MHz) – open loop⁽³⁾					
Phase noise @ 1 kHz			-61		dBc/Hz
Phase noise @ 10 kHz			-89		dBc/Hz
Phase noise @ 100 kHz			-112		dBc/Hz
Phase noise @ 1 MHz			-134		dBc/Hz
Phase noise @ 10 MHz			-151.5		dBc/Hz
Phase noise floor @ 40 MHz			-155		dBc/Hz
VCO A with divider by 4 (750MHz-905MHz) – open loop⁽³⁾					
Phase noise @ 1 kHz			-69		dBc/Hz
Phase noise @ 10 kHz			-96		dBc/Hz
Phase noise @ 100 kHz			-119		dBc/Hz
Phase noise @ 1 MHz			-141		dBc/Hz
Phase noise @ 10 MHz			-154		dBc/Hz
Phase noise floor @ 40 MHz			-155		dBc/Hz
VCO B with divider by 4 (1000MHz-1162.5MHz) – open loop⁽³⁾					
Phase noise @ 1 kHz			-67		dBc/Hz
Phase noise @ 10 kHz			-95		dBc/Hz
Phase noise @ 100 kHz			-118		dBc/Hz
Phase noise @ 1 MHz			-140		dBc/Hz
Phase noise @ 10 MHz			-154		dBc/Hz
Phase noise floor @ 40 MHz			-155		dBc/Hz

- Phase noise SSB.
VCO amplitude setting to value [11].
All the closed-loop performances are specified using a reference clock signal at 76.8 MHz with phase noise of -135dBc/Hz @ 1kHz offset, -145 dBc/Hz @ 10 kHz offset and -149.5dBc/Hz of noise floor.
- Normalized PN = Measured PN – 20log(N) – 10log(F_{PFD}) where N is the VCO divider ratio (N=B*P+A) and F_{PFD} is the comparison frequency at the PFD input.
- Typical phase noise at centre band frequency.

An evaluation kit is available upon request, including a powerful simulation tool (STWPLLSim) that allows a very accurate estimation of the device’s phase noise according to the desired project parameters (VCO frequency, selected output stage, reference clock, frequency step, and so on); refer to [Chapter 8: Application information](#) for more details.

3 Typical performance characteristics

Phase noise is measured with the Agilent E5052A Signal Source Analyzer. All closed-loop measurements are done with $F_{STEP}=200$ kHz, with the F_{PFD} and charge pump current properly set. The loop filter configuration is depicted in [Figure 36: Typical application diagram](#), and the reference clock signal is at 76.8 MHz with phase noise of -135 dBc/Hz at 1kHz offset, -145 dBc/Hz at 10 kHz offset and -149.5 dBc/Hz of noise floor.

Figure 3. VCO A (direct output) open loop phase noise

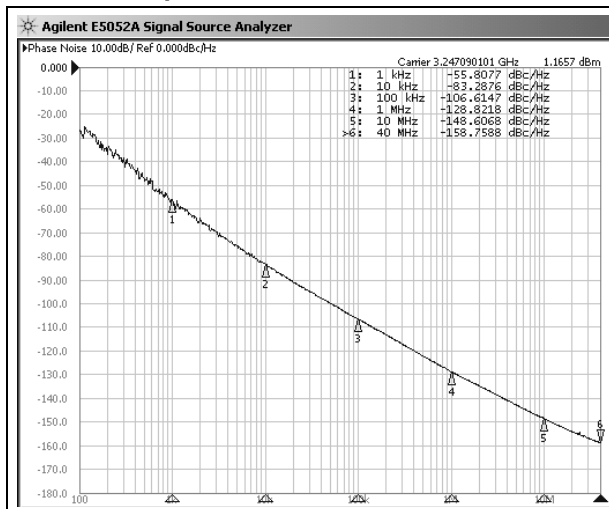


Figure 4. VCO B (direct output) open loop phase noise

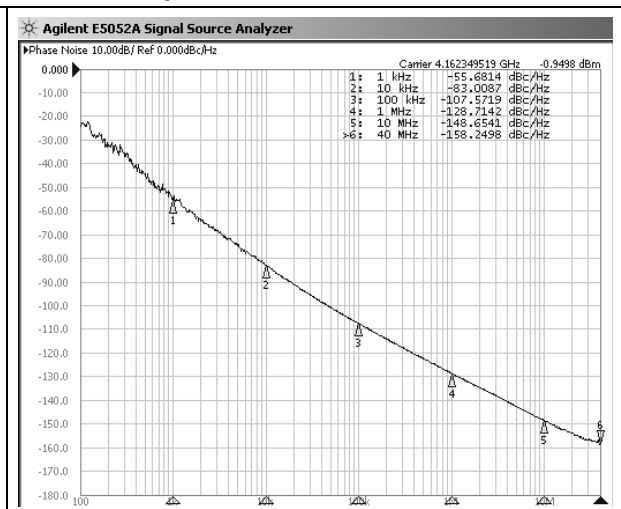


Figure 5. VCO A (direct output) closed loop phase noise at 3.6GHz (F_{STEP}=200kHz; F_{PFD}=200kHz; I_{CP}=3mA)

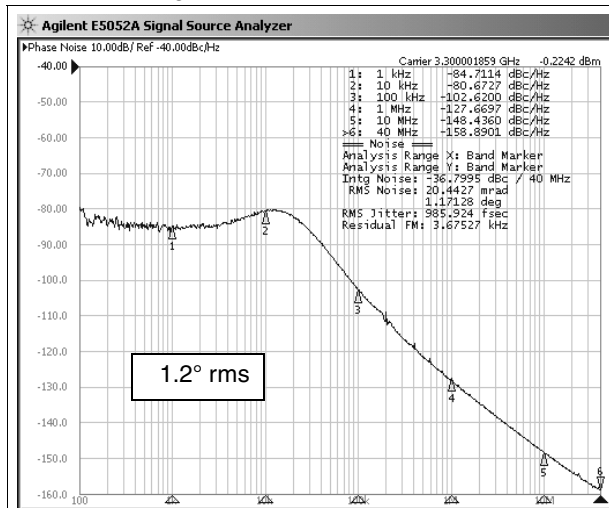


Figure 6. VCO B (direct output) closed loop phase noise at 4.3GHz (F_{STEP}=200kHz; F_{PFD}=200kHz; I_{CP}=4mA)

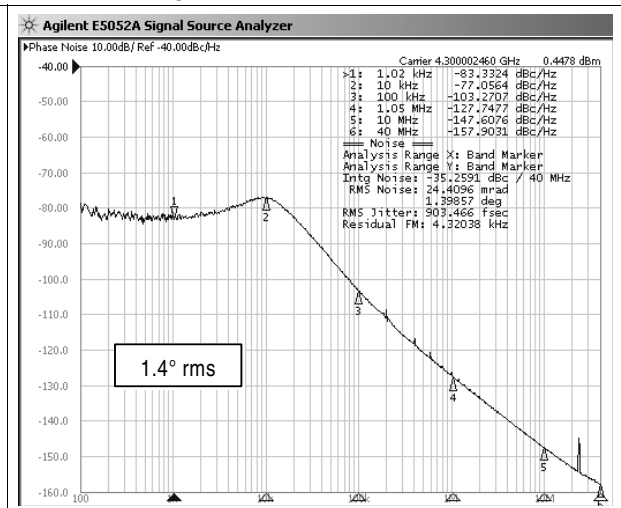


Figure 7. VCO A (div. by 2 output) closed loop phase noise at 1.65GHz (F_{STEP}=200kHz; F_{PPD}=400kHz; I_{CP}=2mA)

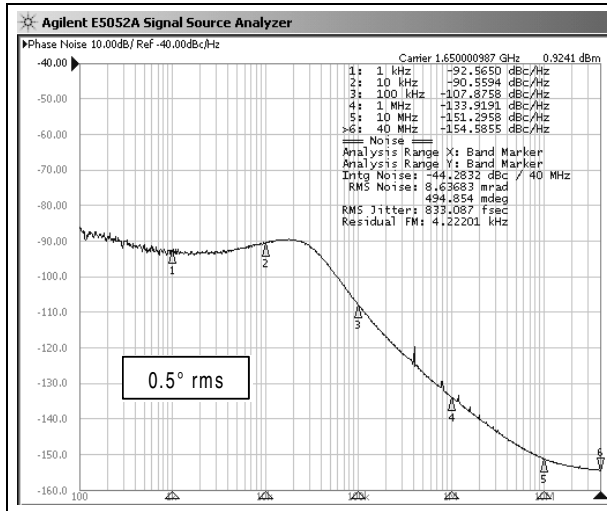


Figure 8. VCO B (div. by 2 output) closed loop phase noise at 2.15GHz (F_{STEP}=200kHz; F_{PPD}=400kHz; I_{CP}=3mA)

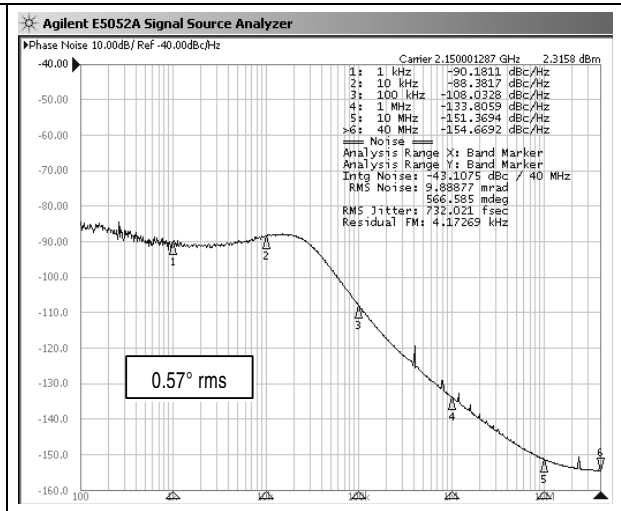


Figure 9. VCO A (div. by 4 output) closed loop phase noise at 825MHz (F_{STEP}=200kHz; F_{PPD}=800kHz; I_{CP}=1.5mA)

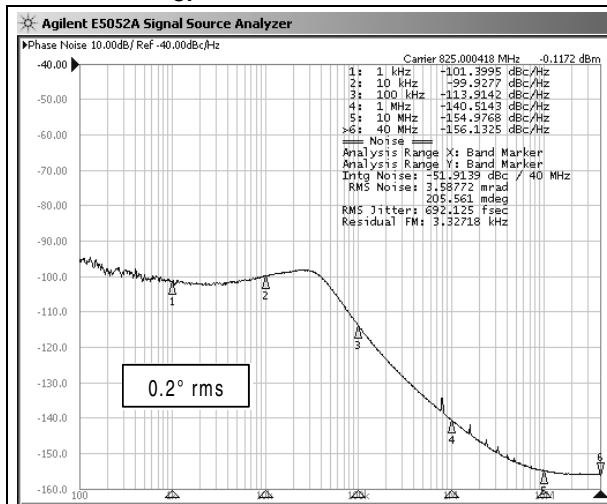


Figure 10. VCO B (div. by 4 output) closed loop phase noise at 1.075GHz (F_{STEP}=200kHz; F_{PPD}=800kHz; I_{CP}=2.5mA)

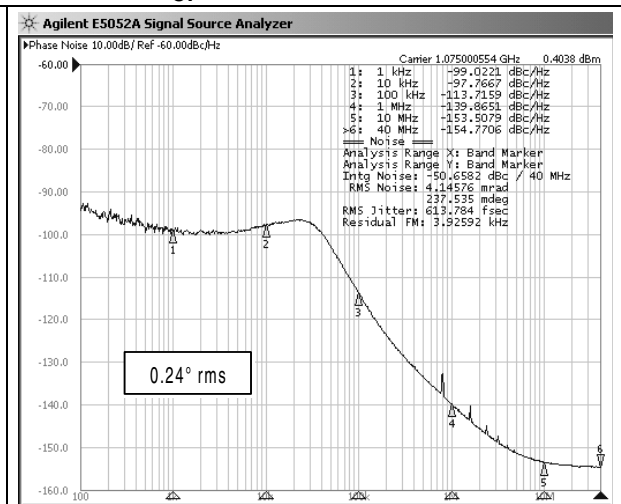


Figure 11. PFD frequency spurs (direct output; $F_{PFD}=200\text{kHz}$)

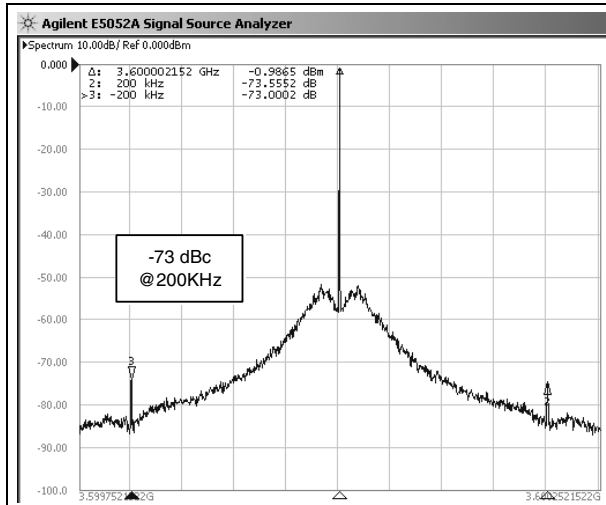


Figure 12. PFD frequency spurs (div. by 2 output; $F_{PFD}=400\text{kHz}$)

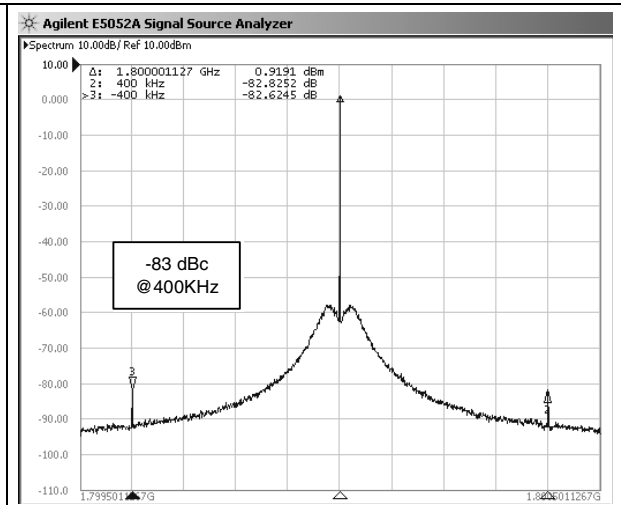


Figure 13. PFD frequency spurs (div. by 4 output; $F_{PFD}=800\text{kHz}$)

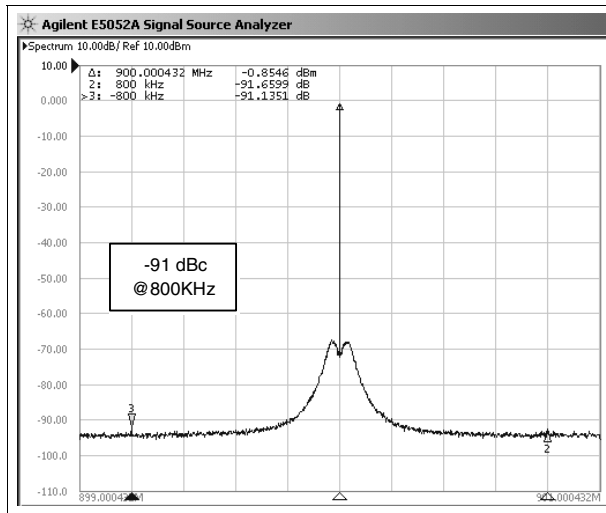
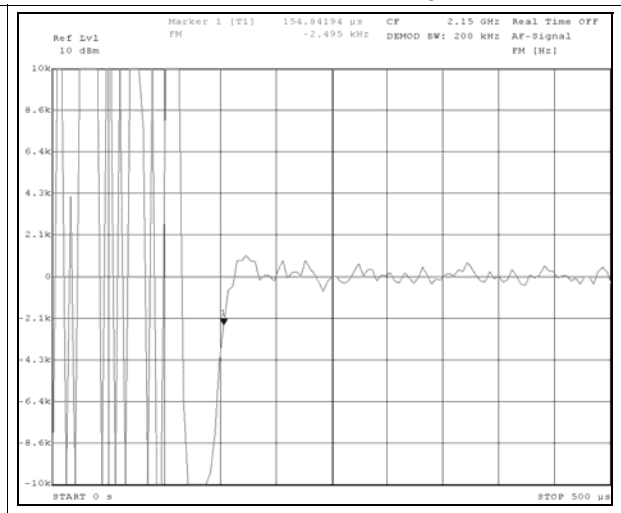


Figure 14. Settling time (final frequency=2.15 GHz; $F_{PFD}=400\text{kHz}$; $I_{CP}=3\text{mA}$)



4 General description

Figure 1: Block diagram shows the separate blocks that, when integrated, form an Integer-N PLL frequency synthesizer.

The STW81102 consists of two internal low-noise VCOs with buffer blocks, a divider by 2, a divider by 4, a low-noise PFD (phase frequency detector), a precise charge pump, a 10-bit programmable reference divider, two programmable counters and a programmable dual-modulus prescaler. The 5-bit A-counter and 12-bit B-counter, in conjunction with the dual-modulus prescaler $P/P+1$ (16/17 or 19/20), implement an N integer divider, where $N = B \cdot P + A$. The division ratio of both reference and VCO dividers is controlled through the selected digital interface (I²C bus or SPI).

The digital interface type is selected by the proper hardware connection of the pin DBUS_SEL (0 V for I²C bus, 3.3 V for SPI).

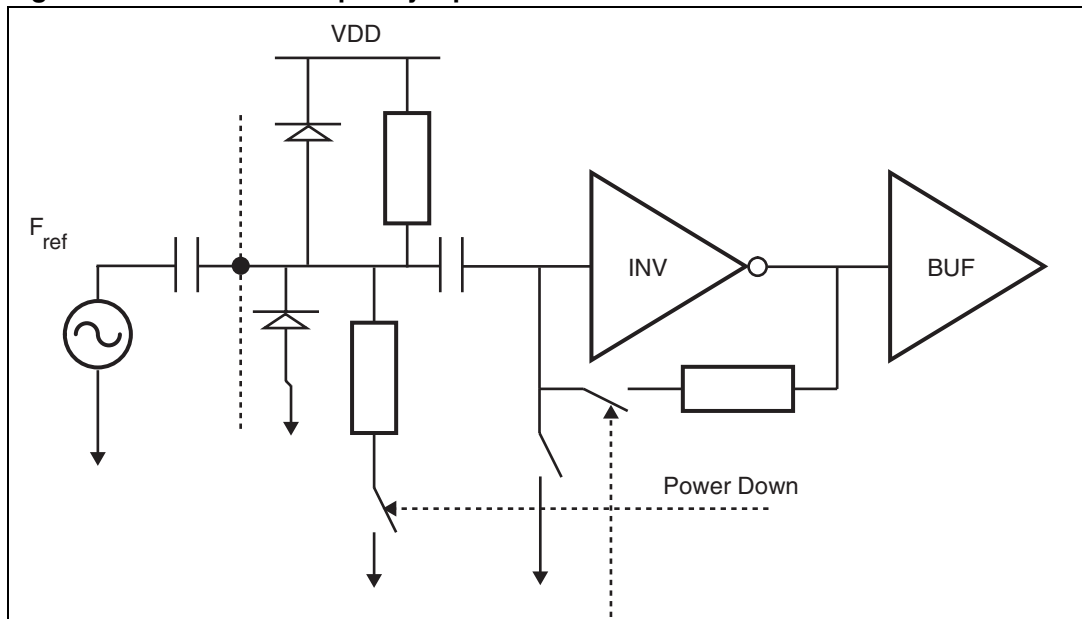
All devices operate with a power supply of 3.3 V and can be powered down when not in use.

5 Circuit description

5.1 Reference input stage

The reference input stage is shown in [Figure 15](#). The resistor network feeds a DC bias at the F_{ref} input while the inverter used as the frequency reference buffer is AC coupled.

Figure 15. Reference frequency input buffer



5.2 Reference divider

The 10-bit programmable reference counter allows division of the input reference frequency to produce the input clock to the PFD. The division ratio is programmed through the digital interface.

5.3 Prescaler

The dual-modulus prescaler $P/P+1$ takes the CML clock from the VCO buffer and divides it down to a manageable frequency for the CMOS A and B counters. The modulus P is programmable and can be set to 16 or 19. The prescaler is based on a synchronous 4/5 core whose division ratio depends on the state of the modulus input.

5.4 A and B counters

The 5-bit A-counter and 12-bit B-counter, in conjunction with the selected dual modulus (16/17 or 19/20) prescaler, make it possible to generate output frequencies which are spaced only by the reference frequency divided by the reference division ratio. Thus, the division ratio and the VCO output frequency are given by these formulas:

$$N = B \times P + A$$

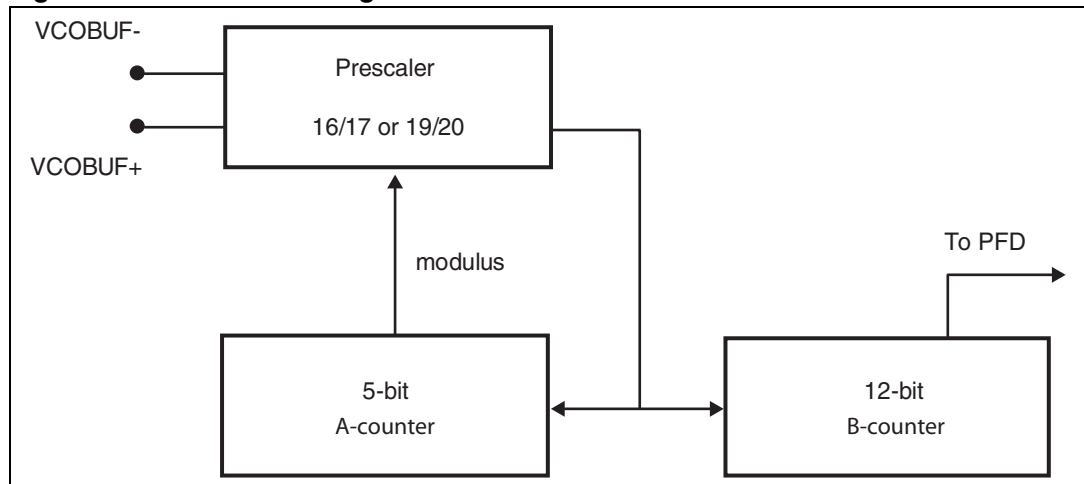
$$F_{VCO} = \frac{(B \times P + A) \times F_{ref}}{R}$$

where:

- F_{VCO}: output frequency of VCO
- P: modulus of dual modulus prescaler (16 or 19 selected through the digital interface)
- B: division ratio of the main counter
- A: division ratio of the swallow counter
- F_{ref}: input reference frequency
- R: division ratio of reference counter
- N: division ratio of PLL

For a correct working of the VCO divider, B must be strictly higher than A. A can take any value ranging from 0 to 31. The range of N can vary from 256 to 65551 (P=16) or from 361 to 77836 (P=19).

Figure 16. VCO divider diagram

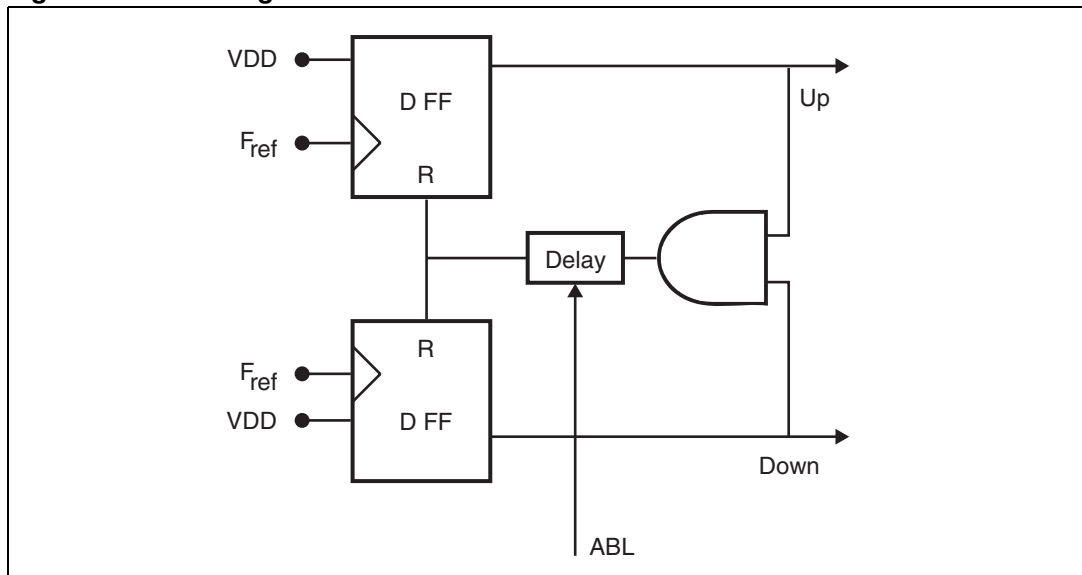


5.5 Phase frequency detector (PFD)

The PFD takes inputs from the reference and the VCO dividers and produces an output proportional to the phase error. The PFD includes a delay gate that controls the width of the anti-backlash pulse. This pulse ensures that there is no dead zone in the PFD transfer function.

Figure 17 is a simplified schematic of the PFD.

Figure 17. PFD diagram



5.6 Lock detect

This signal indicates that the difference between rising edges of both UP and DOWN PFD signals is found to be shorter than the fixed delay (roughly 5 ns). The Lock Detect signal is high when the PLL is locked and low when the PLL is unlocked. Lock Detect consumes current only during PLL transients.

5.7 Charge pump

This block drives two matched current sources, I_{UP} and I_{DOWN} , which are controlled respectively by UP and DOWN PFD outputs. The nominal value of the output current is controlled by an external resistor (connected to the REXT input pin) and a 3-bit word that allows selection among 8 different values.

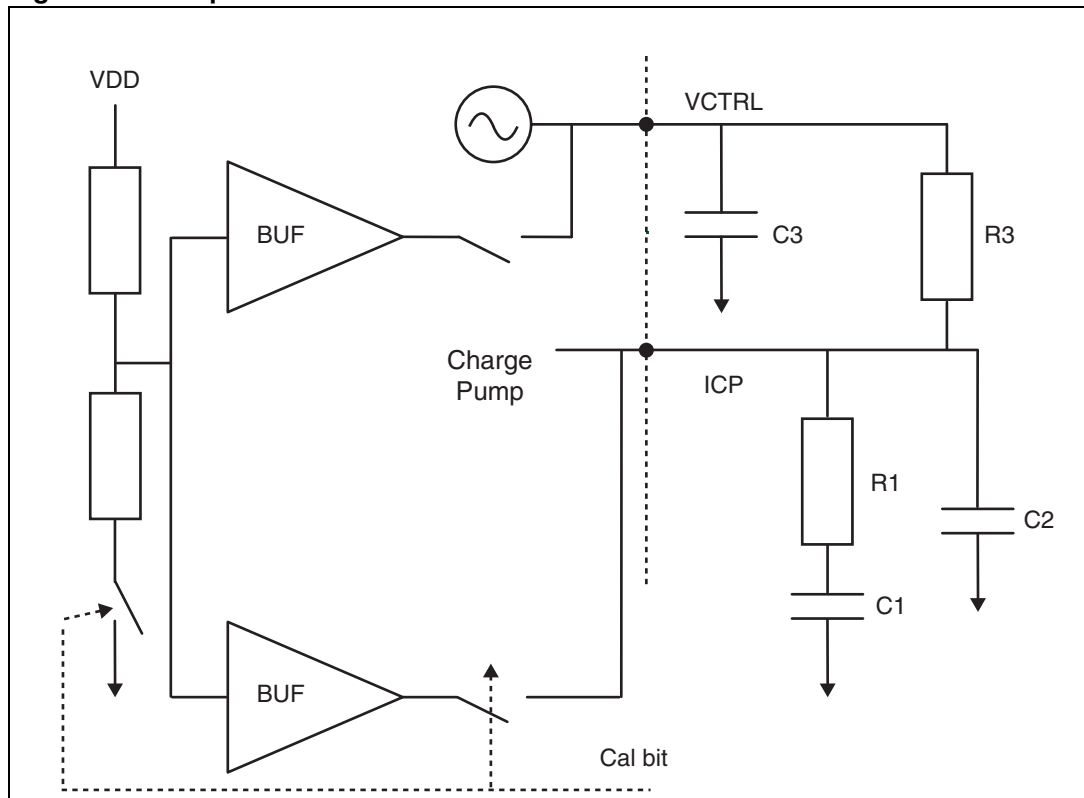
The minimum value of the output current is: $I_{MIN} = 2 \cdot VBG / REXT$ ($VBG \sim 1.17$ V)

Table 7. Current value vs. selection

CPSEL2	CPSEL1	CPSEL0	Current	Value for REXT=4.7 KΩ
0	0	0	I_{MIN}	0.5 mA
0	0	1	$2 \cdot I_{MIN}$	1.0 mA
0	1	0	$3 \cdot I_{MIN}$	1.5 mA
0	1	1	$4 \cdot I_{MIN}$	2.0 mA
1	0	0	$5 \cdot I_{MIN}$	2.5 mA
1	0	1	$6 \cdot I_{MIN}$	3.0 mA
1	1	0	$7 \cdot I_{MIN}$	3.5 mA
1	1	1	$8 \cdot I_{MIN}$	4.0 mA

Note: The current is output on pin ICP. During VCO auto-calibration, the ICP and VCTRL pins are forced to VDD/2

Figure 18. Loop filter connection



5.8 Voltage controlled oscillators

5.8.1 VCO selection

The STW81102 integrates two low-noise VCOs to cover a wide band from:

- 3000 MHz to 3620 MHz and 4000 MHz to 4650 MHz (direct output)
- 1500 MHz to 1810 MHz and 2000 MHz to 2325 MHz (selecting divider by 2)
- 750 MHz to 905 MHz and 1000 MHz to 1162.5 MHz (selecting divider by 4)

The frequency range is 3000 MHz to 3620 MHz for VCO A and 4000 MHz to 4650 MHz for VCO B.

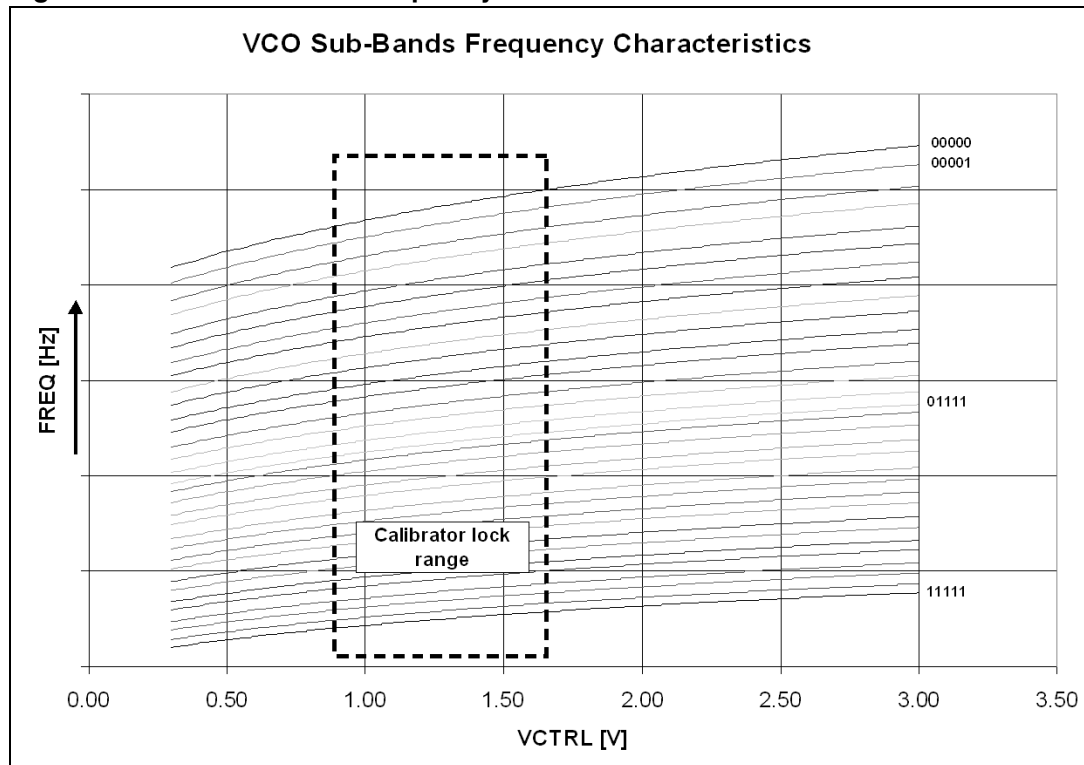
5.8.2 VCO frequency calibration

Both VCOs can operate on 32 frequency ranges that are selected by adding or subtracting capacitors from the resonator. These frequency ranges are intended to cover the wide band of operation and compensate for process variation on the VCO center frequency.

The range is automatically selected when the SERCAL bit is set to 1. The charge pump is inhibited, and the ICP and VCTRL pins are at VDD/2 volts. The ranges are then tested with this VCO input voltage to select the one nearest to the desired output frequency ($F_{OUT} = N \cdot F_{ref}/R$).

After this selection, the SERCAL bit is automatically reset to 0 and the charge pump is once again enabled. To enable a fast settle, the PLL needs only to perform fine adjustment around VDD/2 on the loop filter to reach F_{OUT} .

Figure 19. VCO sub-bands frequency characteristics



The SERCAL bit should be set to 1 at each division ratio change. VCO calibration procedure takes approximately 7 periods of the PFD frequency.

The maximum allowed F_{PFD} to perform the calibration process is 1 MHz. When using a higher F_{PFD} , follow the steps below:

1. Calibrate the VCO at the desired frequency with an F_{PFD} less than 1 MHz.
2. Set the A, B and R divider ratios for the desired F_{PFD} .

VCO calibration auto-restart feature

The VCO calibration auto-restart feature, once activated, allows to restart the calibration procedure when the Lock Detector reports that the PLL has moved to an unlock condition (trigger on '1' to '0' transition of Lock Detector signal).

This situation could happen if the device experiences a significant temperature variation. Once programmed at the initial temperature T_0 inside the operating temperature range (-40 °C to +85 °C), the synthesizer is able to maintain the lock status only if the temperature drift (in either direction) is within the limit specified by the ΔT_{LK} parameter, provided that the final temperature T_1 is still inside the nominal range.

Each VCO featured by STW81102 has its specific ΔT_{LK} parameter reported in Table 5, that is typically lower than the maximum allowable drift ($\Delta T_{MAX}=125$; from -40 °C to +85 °C and vice versa).

By enabling the VCO Calibration Auto-Restart feature (through the CAL_AUTOSTART_EN bit), the part will be able to select again the proper VCO frequency sub-range if the temperature drift exceeds the ΔT_{LK} limit, without any external user command.

5.8.3 VCO voltage amplitude control

The voltage swing of the VCOs can be adjusted over four levels by means of two dedicated programming bits (PLL_A1 and PLL_A0). Higher amplitudes provide best phase noise, whereas lower amplitudes save power.

[Table 8](#) gives the voltage swing level expected on the resonator nodes, the current consumption, and the phase noise at 1 MHz.

Table 8. VCO A performances versus amplitude setting (freq=3.3GHz)

PLL_A[1:0]	Differential voltage swing (Vp)	Current consumption (mA)	PN @1MHz (dBc/Hz)
00	1.1	16	-125
01	1.3	18	-126
10	1.9	27	-128.5
11	2.1	30	-129

Table 9. VCO B performances versus amplitude setting (freq=4.3GHz)

PLL_A[1:0]	Differential voltage swing (Vp)	Current consumption (mA)	PN @1MHz (dBc/Hz)
00	1.1	11	-124
01	1.3	14	-125
10	1.9	20	-127.5
11	2.1	22	-128

5.9 Output stage

The differential output signal of the synthesizer can be selected by software among three different signal paths (Direct, Divider by 2 and Divider by 4) providing multi-band capability.

The selection of the output stage is done by programming properly the PD[4:0] bits.

The output stage is an open-collector structure which is able to meet different requirements over the desired output frequency range by proper connections on the PCB. Refer to [Chapter 8: Application information](#) for more details on PCB connections.

5.9.1 Output Buffer control mode

This control mode allows to enable/disable the output stage by a hardware control pin (EXT_PD, pin#23) while the PLL stays locked at the desired frequency; in such a way a very fast switching time is achieved.

This feature can be useful in designing a ping-pong architecture saving the cost of an external RF switch.

The function of pin#23 (EXT_PD) is set with the OUTBUF_CTRL_EN bit as shown in [Table 10](#).

Table 10. EXT_PD pin function setting

OUTBUF_CTRL_EN	Function of the EXT_PD pin	EXT_PD pin settings
0	Device hardware power down	EXT_PD = 0V → Device ON
		EXT_PD = 3.3V → Device OFF
1	Output Buffer control	EXT_PD = 0V → Output Stage ON
		EXT_PD = 3.3V → Output Stage OFF